

PRODUCT RELIABILITY REPORT  
FOR

**DS1033, Rev B2**

**Dallas Semiconductor**

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Prepared by:

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**Conclusion:**

The following qualification successfully meets the quality and reliability standards required of all Dallas Semiconductor products:

DS1033, Rev B2

In addition, Dallas Semiconductor's continuous reliability monitor program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards. The current status of the reliability monitor program can be viewed at <http://www.maxim-ic.com/TechSupport/dsreliability.html>.

**Device Description:**

A description of this device can be found in the product data sheet. You can find the product data sheet at [http://dbserv.maxim-ic.com/l\\_datasheet3.cfm](http://dbserv.maxim-ic.com/l_datasheet3.cfm).

**Reliability Derating:**

The Arrhenius model will be used to determine the acceleration factor for failure mechanisms that are temperature accelerated.

$$AfT = \exp((Ea/k) * (1/Tu - 1/Ts)) = tu/ts$$

AfT = Acceleration factor due to Temperature  
tu = Time at use temperature (e.g. 55°C)  
ts = Time at stress temperature (e.g. 125°C)  
k = Boltzmann's Constant (8.617 x 10<sup>-5</sup> eV/°K)  
Tu = Temperature at Use (°K)  
Ts = Temperature at Stress (°K)  
Ea = Activation Energy (e.g. 0.7 ev)

The activation energy of the failure mechanism is derived from either internal studies or industry accepted standards, or activation energy of 0.7ev will be used whenever actual failure mechanisms or their activation energies are unknown. All deratings will be done from the stress ambient temperature to the use ambient temperature.

An exponential model will be used to determine the acceleration factor for failure mechanisms, which are voltage accelerated.

$$AfV = \exp(B * (Vs - Vu))$$

AfV = Acceleration factor due to Voltage  
Vs = Stress Voltage (e.g. 7.0 volts)  
Vu = Maximum Operating Voltage (e.g. 5.5 volts)  
B = Constant related to failure mechanism type (e.g. 1.0, 2.4, 2.7, etc.)

The Constant, B, related to the failure mechanism is derived from either internal studies or industry accepted standards, or a B of 1.0 will be used whenever actual failure mechanisms or their B are unknown. All deratings will be done from the stress voltage to the maximum operating voltage. Failure rate data from the operating life test is reported using a Chi-Squared statistical model at the 60% or 90% confidence level (Cf).

The failure rate, Fr, is related to the acceleration during life test by:

$$Fr = X / (ts * AfV * AfT * N * 2)$$

X = Chi-Sq statistical upper limit  
N = Life test sample size

Failure Rates are reported in FITs (Failures in Time) or MTTF (Mean Time To Failure). The FIT rate is related to MTTF by:

$$MTTF = 1/Fr$$

NOTE: MTTF is frequently used interchangeably with MTBF.

The calculated failure rate for this device/process is:

**FAILURE RATE:**                      **MTTF (YRS): 100205**                      **FITS: 1.1**

The parameters used to calculate this failure rate are as follows:

**Cf: 60%**                      **Ea: 0.7**                      **B: 0**                      **Tu: 25 °C**                      **Vu: 5.5 Volts**

The reliability data follows. At the start of this data is the device information. The next section is the detailed reliability data for each stress. The reliability data section includes the latest data available and may contain some generic data. "\*" after DATE CODE denotes specific product data.

**Device Information:**

Process:                      1P, 1M, 0.8um, Ndepletion Diode                      , WJ BPSG                      ,  
 Passivation:                      Laser/TEOS Ox+Alloy +Pass/Nit-GenLasPrb  
 Die Size:                      104 x 77  
 Number of Transistors:                      0  
 Interconnect:                      Aluminum / 1% Silicon / 0.5% Copper  
 Gate Oxide Thickness:                      175 Å

**LOW TEMPERATURE OPERATING LIFE**

DESCRIPTION	DATE CODE	CONDITION	READPOINT	QTY	FAILS	FA#
BIASED BAKE	9506	-20C, 7.0 VOLTS	1000 HRS	77	0	
<b>Total:</b>					<b>0</b>	

**OPERATING LIFE**

DESCRIPTION	DATE CODE	CONDITION	READPOINT	QTY	FAILS	FA#
INFANT LIFE	9506	125C, 7.0 VOLTS	48 HRS	504	0	
HIGH VOLTAGE LIFE	9506	125C, 7.0 VOLTS	1000 HRS	153	0	
BIASED BAKE	9506	125C, 7.0 VOLTS	1000 HRS	77	0	
INFANT LIFE	9613	125C, 7.0 VOLTS	48 HRS	429	0	
HIGH VOLTAGE LIFE	9613	125C, 7.0 VOLTS	1000 HRS	153	0	
BIASED BAKE	9613	125C, 7.0 VOLTS	1000 HRS	77	0	
HIGH VOLTAGE LIFE	9636	125C, 7.0 VOLTS	1000 HRS	116	0	
HIGH VOLTAGE LIFE	9908	125C, 7.0 VOLTS	1000 HRS	116	0	
HIGH VOLTAGE LIFE	9909	125C, 7.0 VOLTS	1000 HRS	116	0	
<b>Total:</b>					<b>0</b>	

**FAILURE RATE:**                      **MTTF (YRS): 100205**                      **FITS: 1.1**